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(54) Title: WAFER CLEANING APPARATUS

(57) Abstract

A method and apparatus for cleaning a wafer oriented vertically is provided. The apparatus includes a first brush and a second brush located horizontally from the first brush. During unloading of the wafer after cleaning, the wafer is located vertically between the first and second brushes and on a pair of rollers. A finger tip located vertically above the region between the first and second brushes contacts an edge of the wafer and thus hold the wafer in the precise unloading position at which a wafer transfer robotic arm has been programmed to engage/disengage the wafer. Accordingly, the wafer is reliably and repeatedly engaged by the robotic arm.